

**Integrated chip package structure using metal substrate and method of
manufacturing the same**

Appl. No. : 10/055,560 Confirmation No. : 6103
Applicant : Mou-Shiung Lin,
Jin-Yuan Lee,
Ching-Cheng Huang
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TC/A.U. : 2813
Examiner : Mitchell, James M
Docket No. : MEGP0009USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

5 **RESPONSE TO OFFICE COMMUNICATION**

Sir:

In response to the Office Communication mailed Mar. 9, 2009, please amend the above-identified application and consider the remarks as follows:

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.